Silicon NPN Epitaxial

HITACHI

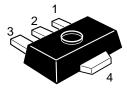
ADE-208-1146 (Z) 1st. Edition Mar. 2001

Application

Low frequency power amplifier

Outline

UPAK



- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector (Flange)



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	30	V
Collector to emitter voltage	V _{CEO}	25	V
Emitter to base voltage	V_{EBO}	5	V
Collector current	I _c	1	A
Collector peak current	i _{C(peak)} *1	1.5	A
Collector power dissipation	P _C *2	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. $PW \le 10 \text{ ms}$, Duty cycle $\le 20\%$.

2. Value on the alumina ceramic board (12.5 \times 20 \times 0.7 mm)

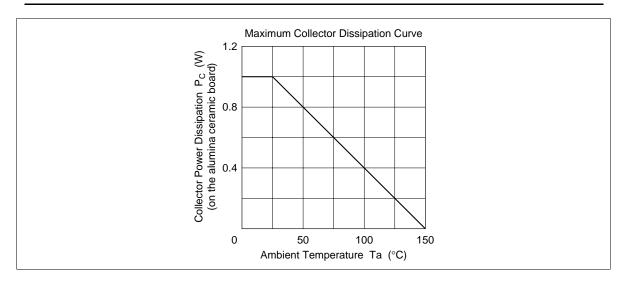
Electrical Characteristics ($Ta = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	30	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	25	_	_	V	I_{C} = 1 mA, R_{BE} = ∞
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	_	_	V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I _{CBO}	_	_	0.1	μΑ	$V_{CB} = 20 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_		0.1	μΑ	$V_{EB} = 4 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE} *1	85	_	240		$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}, \text{ Pulse}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	0.15	0.3	V	I _C = 0.8 A, I _B = 0.08 A, Pulse
Base to emitter saturation voltage	$V_{BE(sat)}$	_	0.9	1.0	V	I _C = 0.8 A, I _B = 0.08 A, Pulse
Gain bandwidth product	f _T	_	240	_	MHz	$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}, \text{ Pulse}$
Collector output capacitance	Cob	_	22	_	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

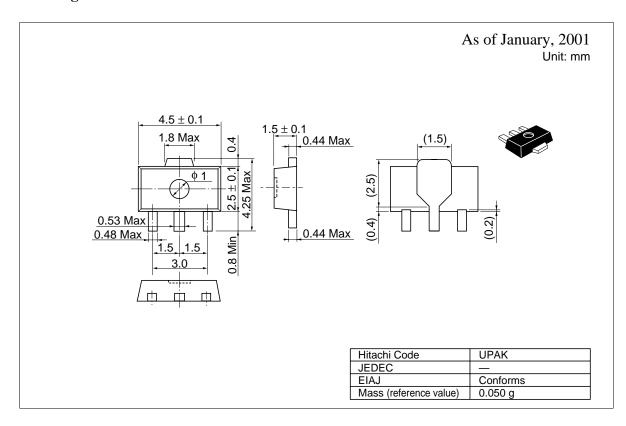
Note: 1. The 2SD1366A is grouped by h_{FE} as follows.

Mark	AC	AD
h _{FE}	85 to 170	120 to 240

See characteristic curves of 2SD1366.



Package Dimensions



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Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : http://semiconductor.hitachi.com/ Europe http://www.hitachi-eu.com/hel/ecg Asia http://sicapac.hitachi-asia.com Japan http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

> Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Tel: <44> (1628) 585000

Berkshire SL6 8YA, United Kingdom Tel: <886>-(2)-2718-3666 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577

Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building.

Taipei (105), Taiwan Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw

Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852>-(2)-735-9218

Hitachi Asia (Hong Kong) Ltd.

Fax: <852>-(2)-730-0281 URL: http://www.hitachi.com.hk

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